



Product Change Notification - KSRA-08NNFY461 [\(Printer Friendly\)](#)

Date: 18 Aug 2017

Product Category: 16-Bit - Microcontrollers and Digital Signal Controllers; 8-bit PIC Microcontrollers

Notification subject: CCB 2800 Initial Notice: Qualification of CuPdAu bond wire for selected products of 200K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site

Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products of 200K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site.

Pre Change:

Using gold (Au) bond wire and C194 lead frame material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire and C194 lead frame material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB assembly site	NSEB assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD

Lead frame material	C194	C194
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Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

September 18, 2017 (1738)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

	December 2016					→	August 2017					September 2017			
Workweek	49	50	51	52	53		31	32	33	34	35	36	37	38	39
Initial PCN Issue Date					X										
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date														X	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

December 29, 2016: Issued initial notification.

January 11, 2017: Re-issued initial notification to change the lead frame material from A194 to C194 for consistency.

August 18, 2017: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on September 18, 2017

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_KSRA-08NNFY461_Affected CPN.pdf](#)
[PCN_KSRA-08NNFY461_Qual Report.pdf](#)
[PCN_KSRA-08NNFY461_Affected CPN.xlsx](#)

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